

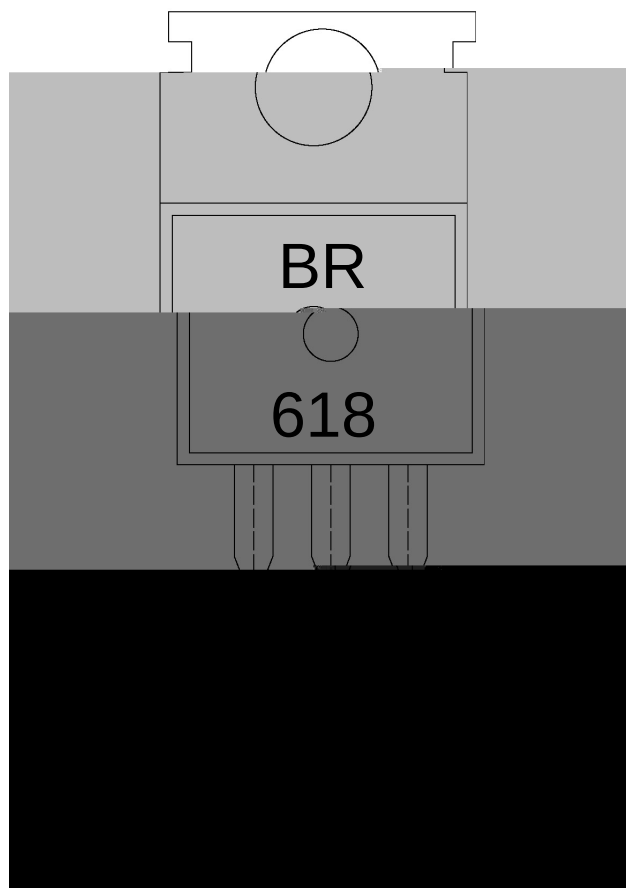
BR618

Rev.G Oct.-2018

DATA SHEET

Architectural floor plan of a building. The plan includes a large central hall (C1), a smaller room (C2), and a kitchen (C3). It also shows a staircase (B), a bathroom (A), and a bedroom (E). The plan is detailed with dimensions, door swings, and furniture placement. A large black rectangular area is present in the upper right portion of the plan.

/ Marking Instructions



б " X

BR X

618 X

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Note:

BR:

618:

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BR X

618 X

BR X 618 X

Company Code

Product Type.

Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



说明

1. 预加热: 25~150 °C, 时间: 60~90sec;
2. 峰值温度: 255 °C, 持续时间: 5~0.5sec;
3. 冷却速度: 2~10 °C/sec.

Note:

- 1.Preheating:25~150 °C, Time:60~90sec.
- 2.Peak Temp.:255 °C, Duration:5~0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

预加热: 270 °C ± 5 °C, 时间: 10 ± 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

散装 / BULK

Package Type	Units					Dimension (unit mm ³)		

管装 / TUBE

Package Type	Units					Dimension (unit mm ³)		

/ Notices